Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in an MLPAK33 (SOT8002-2) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Trench MOSFET technology
- MLPAK33 package (3.3 x 3.3 mm footprint)
- · Low thermal resistance
- Low 0.8 mm profile

3. Applications

· Active clamp circuits

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit | |
|-------------------|----------------------------------|---|-----|-----|-----|------|------|--|
| V _{DS} | drain-source voltage | T _j = 25 °C | | - | - | -100 | V | |
| V_{GS} | gate-source voltage | | | -20 | - | 20 | V | |
| I _D | drain current | V _{GS} = -10 V; T _{amb} = 25 °C | [1] | - | - | -0.7 | Α | |
| Static characte | Static characteristics | | | | | | | |
| R _{DSon} | drain-source on-state resistance | V_{GS} = -10 V; I_D = -0.7 A; T_j = 25 °C | | - | 930 | 1500 | mΩ | |

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².



5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|---------------------------------|----------------|
| 1 | S | source | 1 2 3 4 | |
| 2 | S | source | | D |
| 3 | S | source |] | |
| 4 | G | gate | | G $($ |
| 5 | D | drain | | |
| 6 | D | drain | l Uaaal | S |
| 7 | D | drain | 8 7 6 5 MI DAK22 (COT9002 2) | 017aaa094 |
| 8 | D | drain | MLPAK33 (SOT8002-2) | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | | | | | |
|---------------|---------|---|-----------|--|--|--|--|
| | Name | Description | Version | | | | |
| PXP1500-100QS | | plastic thermal enhanced surface mounted package; mini leads; 8 terminals; pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body | SOT8002-2 | | | | |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|---------------|--------------|
| PXP1500-100QS | 9AM |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|----------------------|--|--|-----|-----|-------|------|
| V _{DS} | drain-source voltage | T _j = 25 °C | | - | -100 | V |
| V _{GS} | gate-source voltage | | | -20 | 20 | V |
| I _D | drain current | V _{GS} = -10 V; T _{amb} = 25 °C | [1] | - | -0.7 | Α |
| | | V _{GS} = -10 V; T _{amb} = 100 °C | [1] | - | -0.4 | Α |
| | | V _{GS} = -10 V; T _{sp} = 25 °C | | - | -1.4 | Α |
| I _{DM} | peak drain current | T_{amb} = 25 °C; single pulse; $t_p \le 10 \mu s$ | | - | -3 | Α |
| P _{tot} | total power dissipation | T _{amb} = 25 °C | [1] | - | 1.4 | W |
| | | T _{sp} = 25 °C | | - | 6.1 | W |
| Tj | junction temperature | | | -55 | 150 | °C |
| T _{amb} | ambient temperature | | | -55 | 150 | °C |
| T _{stg} | storage temperature | | | -65 | 150 | °C |
| Source-drain | n diode | | | | | |
| Is | source current | T _{amb} = 25 °C | [1] | - | -0.66 | Α |
| Avalanche r | uggedness | | 1 | 1 | | |
| E _{DS(AL)S} | non-repetitive drain- source avalanche energy | $T_{j(init)}$ = 25 °C; I_D = -0.6 A; DUT in valanche (unclamped) | | - | 7 | mJ |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².

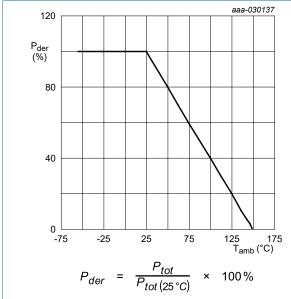


Fig. 1. Normalized total power dissipation as a function of ambient temperature

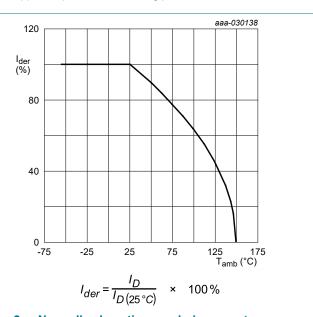


Fig. 2. Normalized continuous drain current as a function of ambient temperature

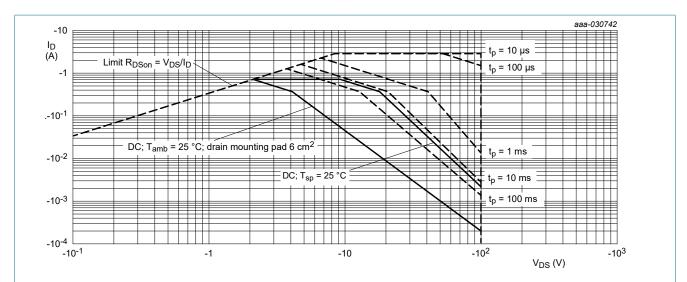


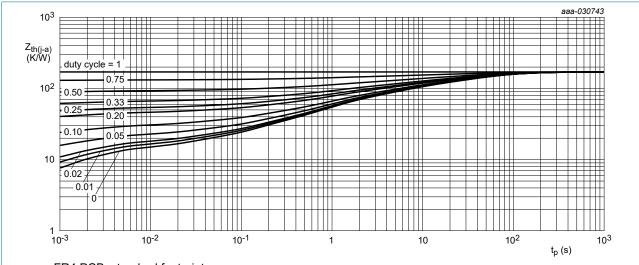
Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

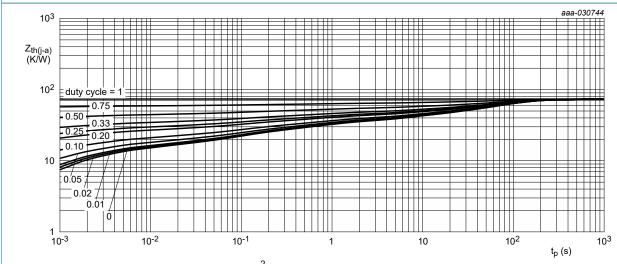
| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|----------------------|--|-------------|-----|-----|------|------|------|
| R _{th(j-a)} | thermal resistance from | in free air | [1] | - | 170 | 205 | K/W |
| junction to ambient | junction to ambient | | [2] | - | 75 | 90 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | | - | 17.2 | 20.5 | K/W |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².



FR4 PCB, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for drain 6 cm²

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|---------------------------------------|---|---|------|----------|------|------|
| Static chara | ecteristics | | | | | |
| V _{(BR)DSS} | drain-source breakdown voltage | I_D = -250 μ A; V_{GS} = 0 V; T_j = 25 °C | -100 | - | - | V |
| V_{GSth} | gate-source threshold voltage | I_D = -250 μ A; V_{DS} = V_{GS} ; T_j = 25 °C | -2 | -3 | -4 | V |
| I _{DSS} | drain leakage current | V _{GS} = 0 V; V _{DS} = -100 V; T _j = 25 °C | - | - | -1 | μΑ |
| I _{GSS} | gate leakage current | V _{GS} = -20 V; V _{DS} = 0 V; T _j = 25 °C | - | - | -100 | nA |
| | | V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C | - | - | 100 | nA |
| R_{DSon} | drain-source on-state | $V_{GS} = -10 \text{ V}; I_D = -0.7 \text{ A}; T_j = 25 \text{ °C}$ | - | 930 | 1500 | mΩ |
| | resistance | V _{GS} = -10 V; I _D = -0.7 A; T _j = 150 °C | - | 2000 | 3165 | mΩ |
| | | V _{GS} = -6 V; I _D = -0.6 A; T _j = 25 °C | - | 1000 | 1700 | mΩ |
| g _{fs} | forward transconductance | $V_{DS} = -5 \text{ V}; I_D = -0.7 \text{ A}; T_j = 25 \text{ °C}$ | - | 1.6 | - | S |
| R_G | gate resistance | f = 1 MHz | - | 26 | - | Ω |
| Dynamic ch | aracteristics | | | | | |
| Q _{G(tot)} total gate charge | V_{DS} = -50 V; I_{D} = -0.6 A; V_{GS} = -10 V; T_{j} = 25 °C | - | 3.1 | 4.5 | nC | |
| | | $V_{DS} = -50 \text{ V}; I_D = -0.6 \text{ A}; V_{GS} = -6 \text{ V};$ | - | 2.1 | 3.1 | nC |
| Q _{GS} | gate-source charge | T _j = 25 °C | - | 0.6 | - | nC |
| Q_{GD} | gate-drain charge | | - | 0.9 | - | nC |
| C _{iss} | input capacitance | V _{DS} = -50 V; f = 1 MHz; V _{GS} = 0 V; | - | 159 | - | pF |
| C _{oss} | output capacitance | T _j = 25 °C | - | 8 | - | pF |
| C _{rss} | reverse transfer capacitance | | - | 4.5 | - | pF |
| t _{d(on)} | turn-on delay time | $V_{DS} = -50 \text{ V}; I_D = -0.6 \text{ A}; V_{GS} = -6 \text{ V};$ | - | 5 | - | ns |
| t _r | rise time | $R_{G(ext)} = 5 \Omega; T_j = 25 °C$ | - | 17 | - | ns |
| $t_{d(off)}$ | turn-off delay time | 1 | - | 5 | - | ns |
| t _f | fall time | 1 | - | 12 | - | ns |
| Source-drai | in diode | | ' | <u> </u> | | ' |
| V _{SD} | source-drain voltage | $I_S = -0.7 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$ | - | -0.8 | -1.2 | V |
| t _{rr} | reverse recovery time | $I_S = -0.6 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s};$ | - | 24 | - | ns |
| Q _r | recovered charge | $V_{GS} = -6 \text{ V}; V_{DS} = -40 \text{ V}; T_j = 25 \text{ °C}$ | - | 20 | - | nC |

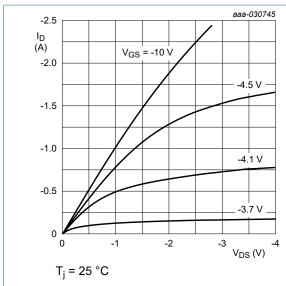


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

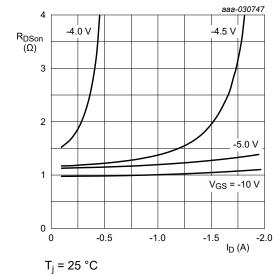


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

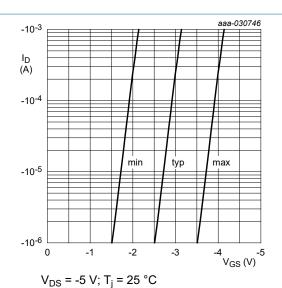


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

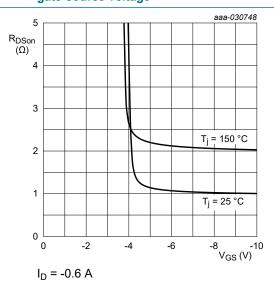


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

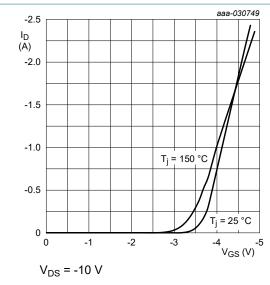


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

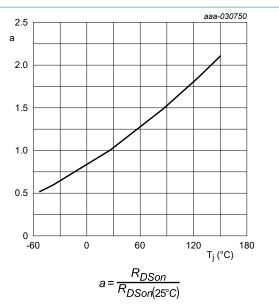


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

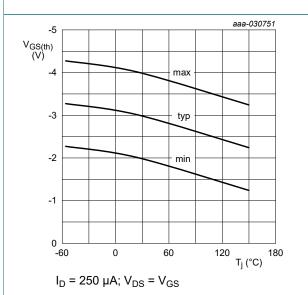
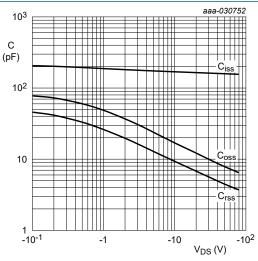


Fig. 12. Gate-source threshold voltage as a function of junction temperature



 $f = 1 MHz; V_{GS} = 0 V$

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

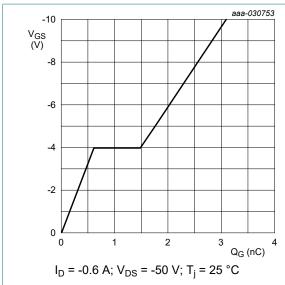


Fig. 14. Gate-source voltage as a function of gate charge; typical values

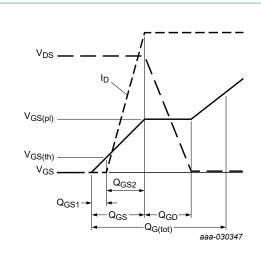


Fig. 15. Gate charge waveform definitions

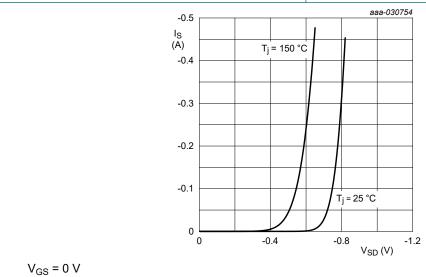
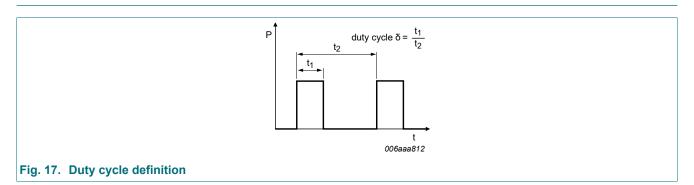
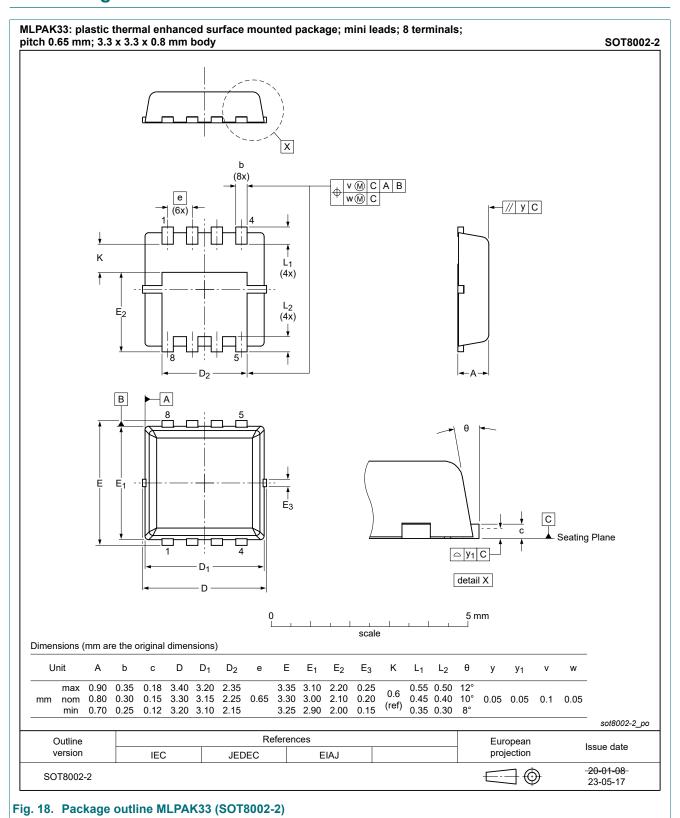


Fig. 16. Source current as a function of source-drain voltage; typical values

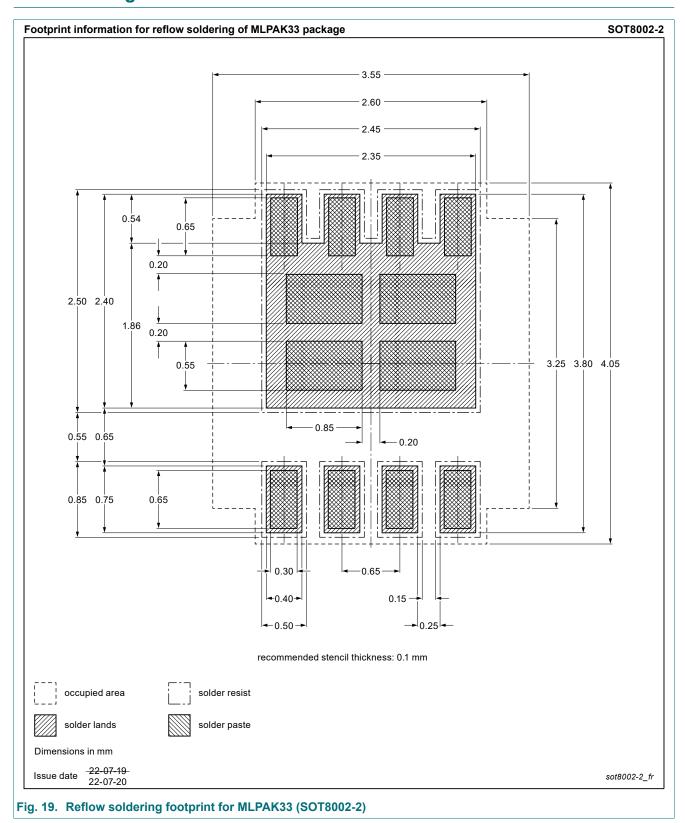
11. Test information



12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

| Table 6. Revision mistory | | | | | | | |
|---------------------------|---------------------|---|---------------|-------------------|--|--|--|
| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes | | | |
| PXP1500-100QS v.3 | 20230731 | Product data sheet | - | PXP1500-100QS v.2 | | | |
| Modifications: | Chapter "Package or | Chapter "Package outline": drawing update | | | | | |
| PXP1500-100QS v.2 | 20211120 | Product data sheet | - | PXP1500-100QS v.1 | | | |
| PXP1500-100QS v.1 | 20200507 | Product data sheet | - | - | | | |

15. Legal information

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| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|-----------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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| Product [short] data sheet | Production | This document contains the product specification. |

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